

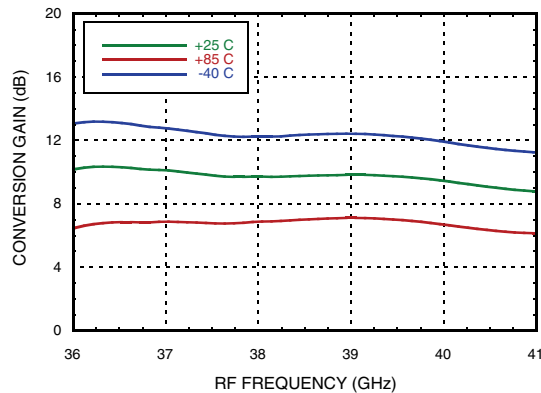
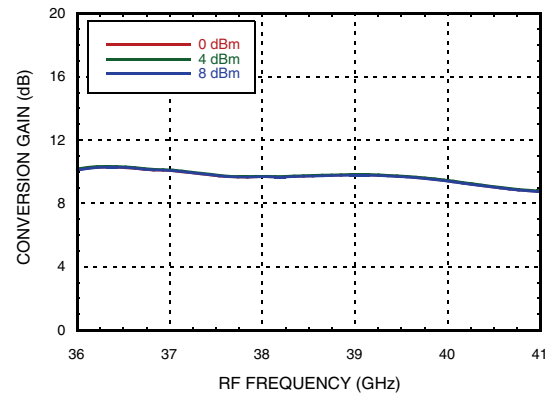
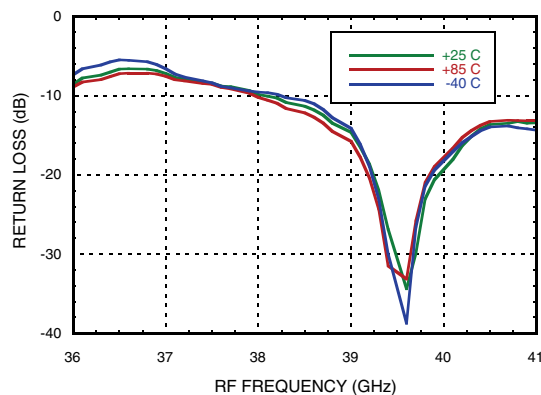
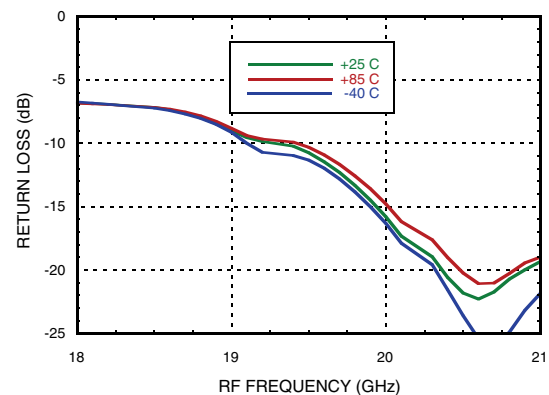
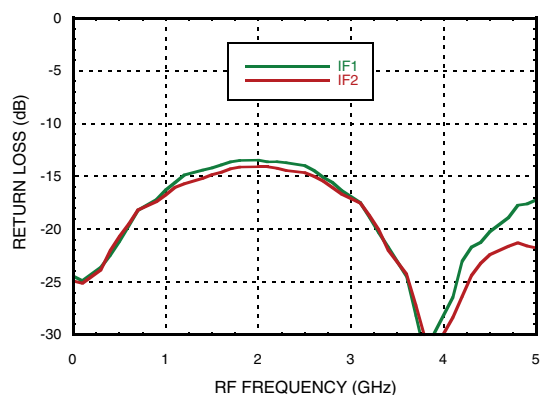
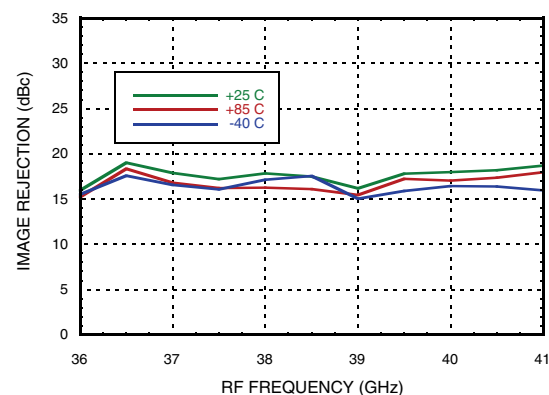


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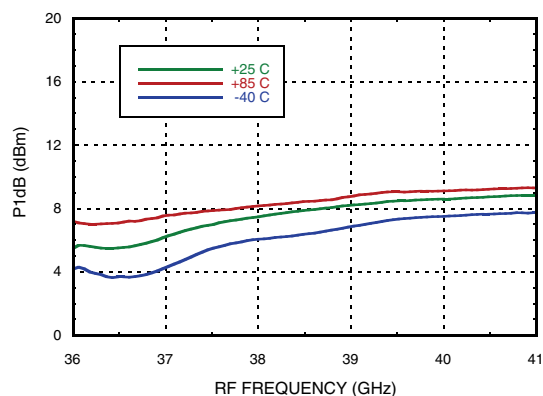
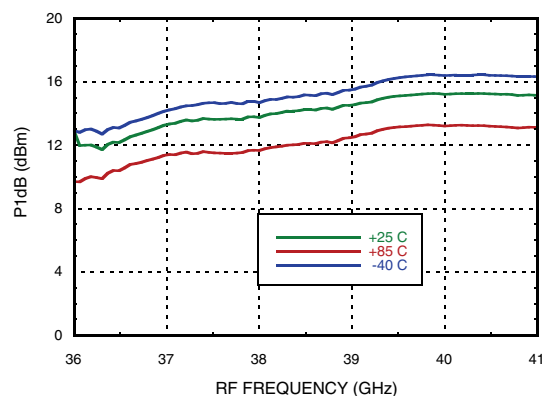
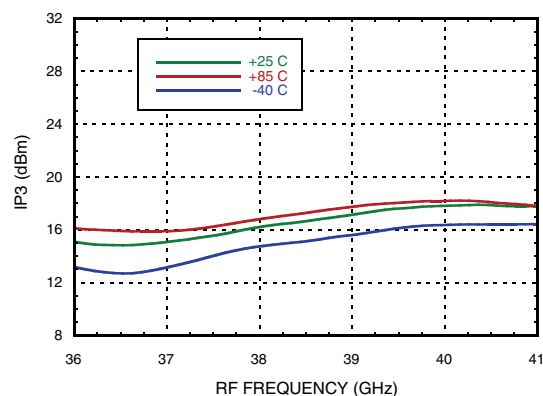
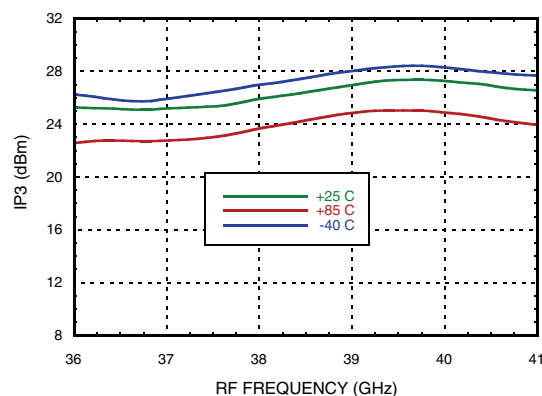
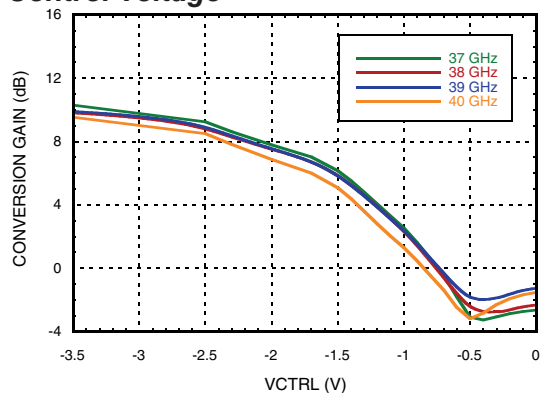
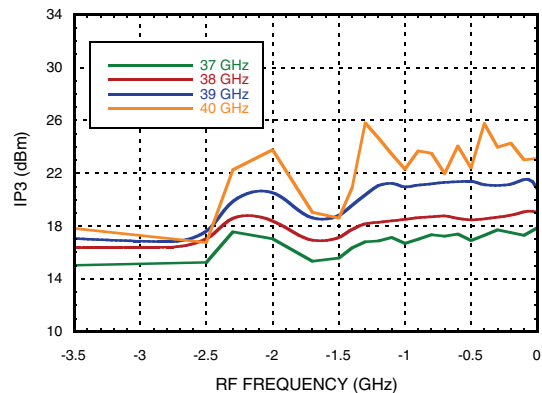
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Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 2350 MHz

Conversion Gain, USB vs. Temperature

Conversion Gain, USB vs. LO Drive

RF Return Loss vs. Temperature

LO Return Loss vs. Temperature

IF Return Loss ^[1]

Sideband Rejection vs. Temperature


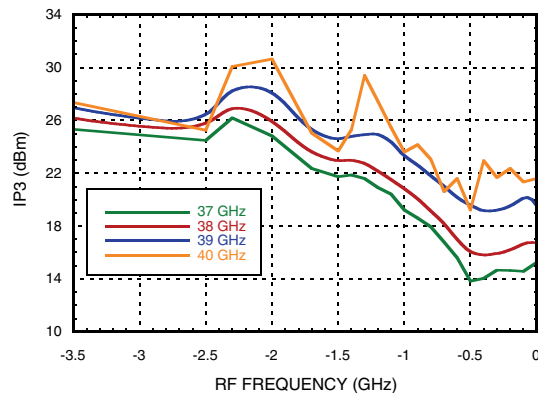
[1] Data taken without external IF 90° hybrid

Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 2350 MHz

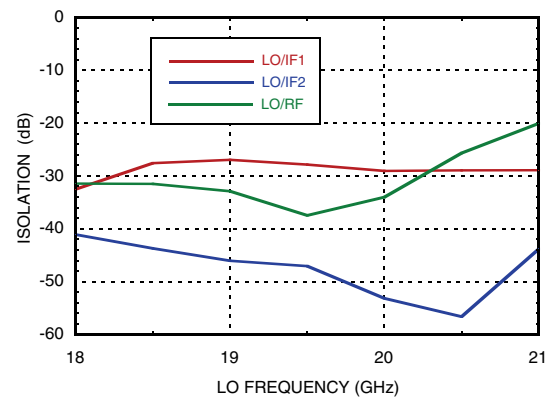
Input P1dB, USB vs. Temperature

Output P1dB, USB vs. Temperature

Input IP3, USB vs. Temperature

Output IP3, USB vs. Temperature

Conversion Gain, USB vs. Control Voltage

Input IP3, USB vs. Control Voltage


Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 2350 MHz

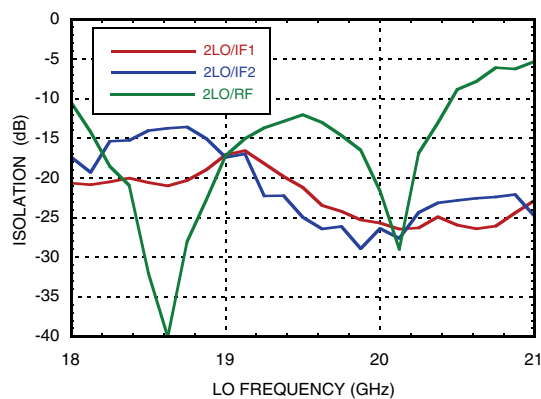
Output IP3, USB vs. Control Voltage



LO Isolation



2LO Isolation





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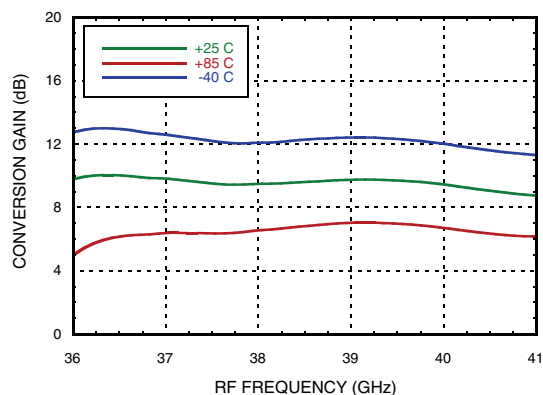


HMC6787ALC5A

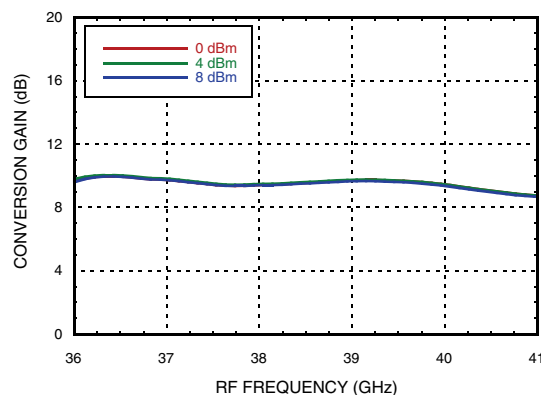
GaAs MMIC I/Q UPCONVERTER 37 - 40 GHz

Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 3000 MHz

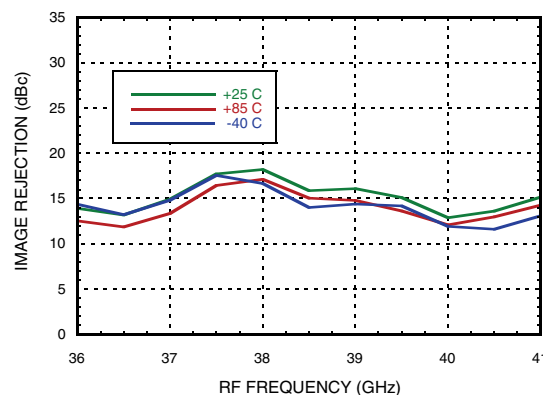
Conversion Gain, USB vs. Temperature



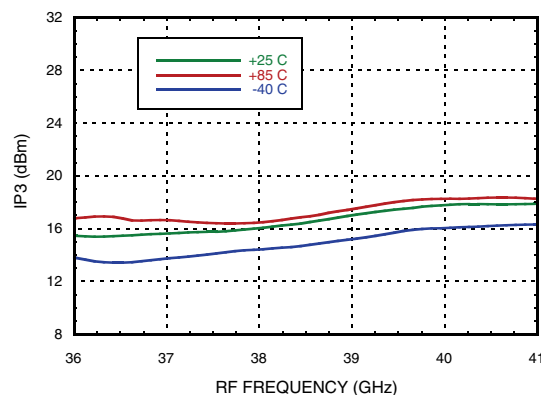
Conversion Gain, USB vs. LO Drive



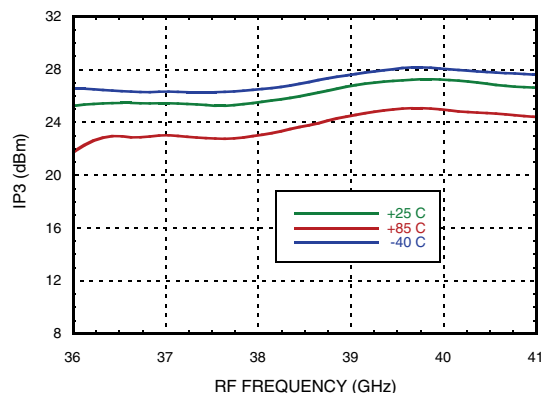
Sideband Rejection vs. Temperature



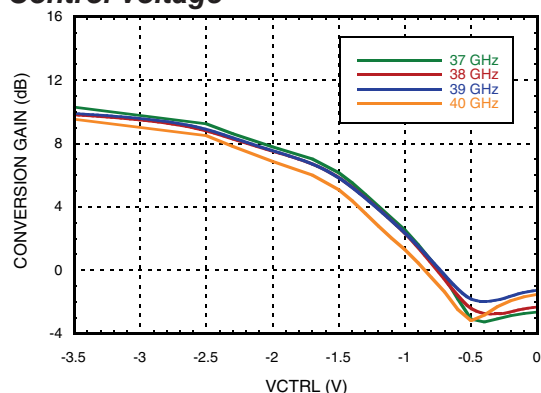
Input IP3, USB vs. Temperature



Output IP3, USB vs. Temperature

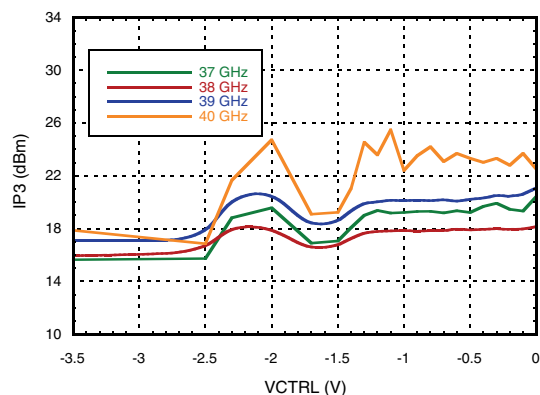


Conversion Gain, USB vs. Control Voltage

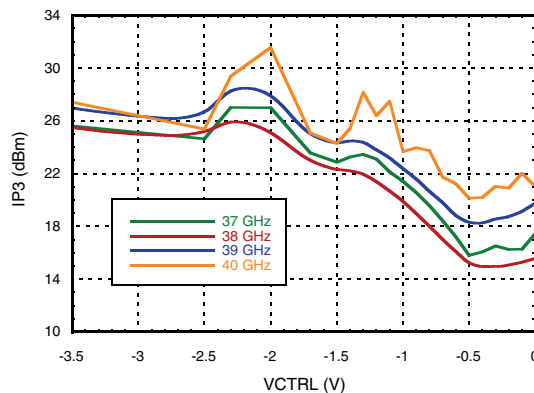


Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 3000 MHz

Input IP3, USB vs. Control Voltage

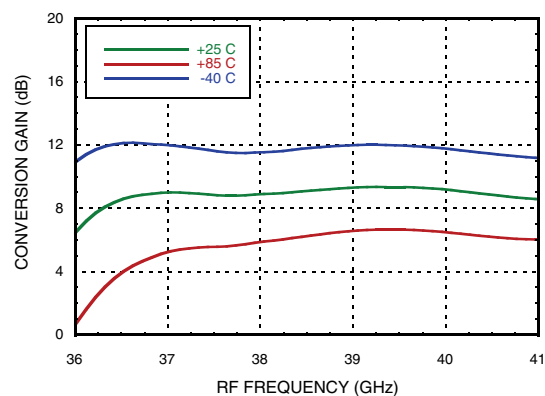


Output IP3, USB vs. Control Voltage

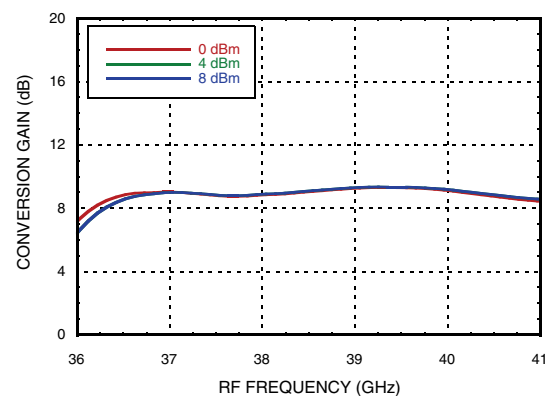


Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 3750 MHz

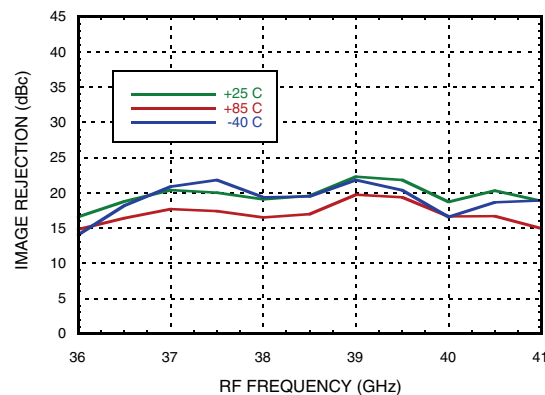
Conversion Gain, USB vs. Temperature



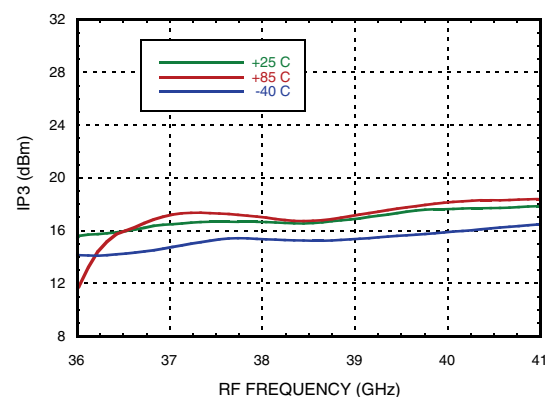
Conversion Gain, USB vs. LO Drive



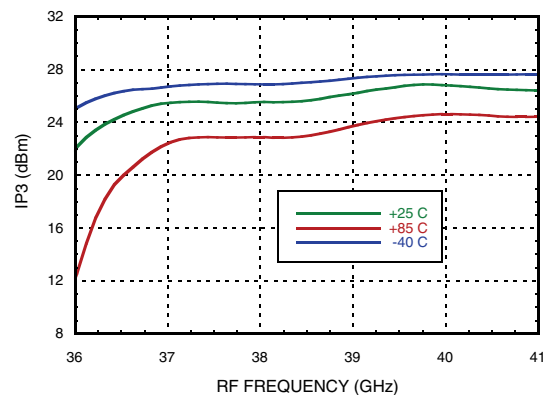
Sideband Rejection vs. Temperature



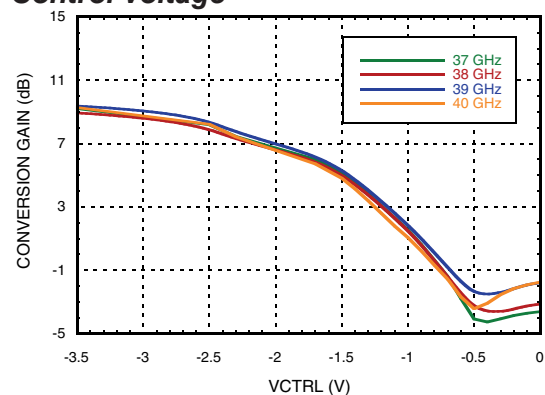
Input IP3, USB vs. Temperature



Output IP3, USB vs. Temperature



Conversion Gain, USB vs. Control Voltage





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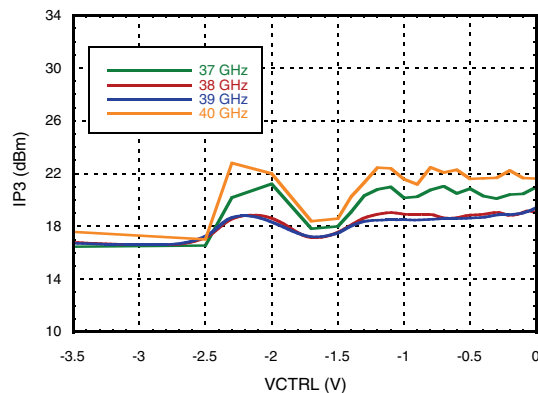


HMC6787ALC5A

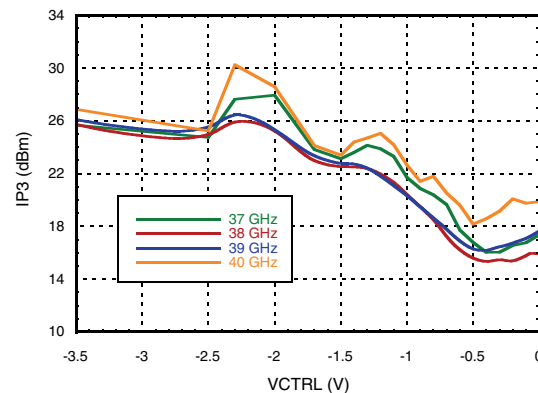
GaAs MMIC I/Q UPCONVERTER 37 - 40 GHz

Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 3750 MHz

Input IP3, LSB vs. Control Voltage



Output IP3, LSB vs. Control Voltage



[1] Data taken without external IF 90° hybrid

[2] All values in dBc below RF power level (2LO + IF) USB



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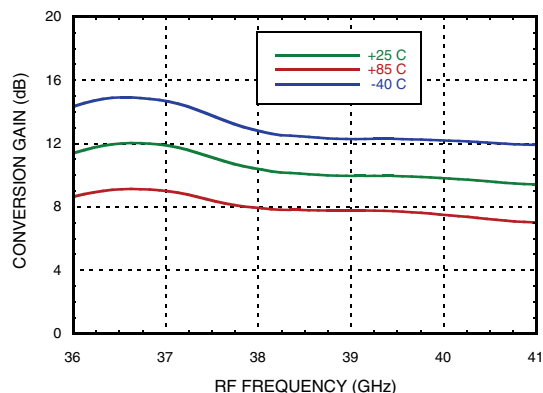


HMC6787ALC5A

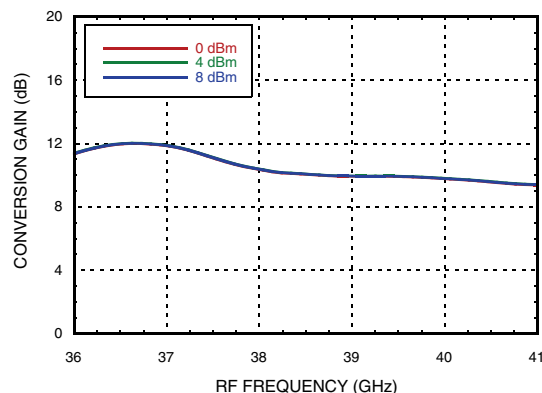
GaAs MMIC I/Q UPCONVERTER 37 - 40 GHz

Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 1000 MHz

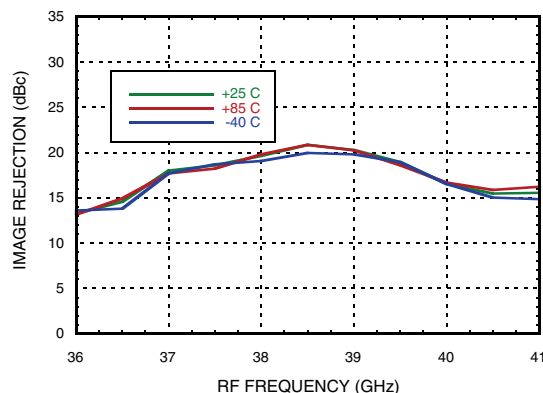
Conversion Gain, USB vs. Temperature



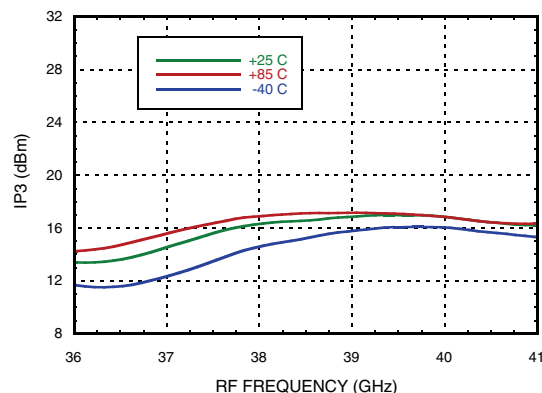
Conversion Gain, USB vs. LO Drive



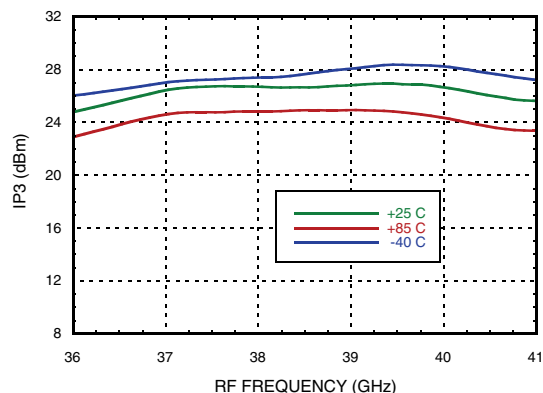
Sideband Rejection vs. Temperature



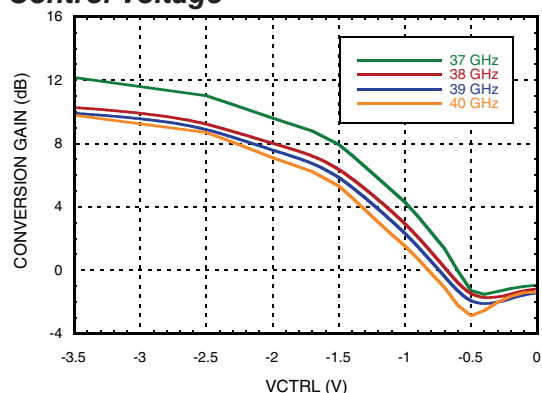
Input IP3, USB vs. Temperature



Output IP3, USB vs. Temperature

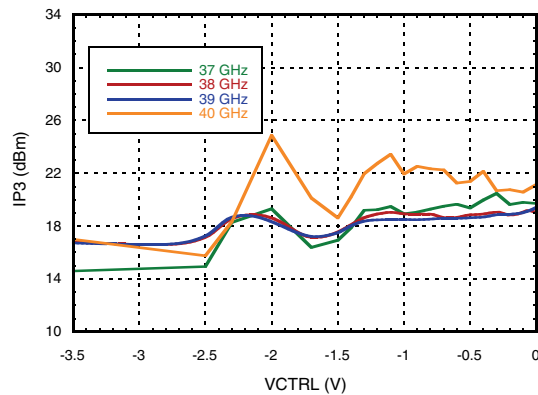


Conversion Gain, USB vs. Control Voltage

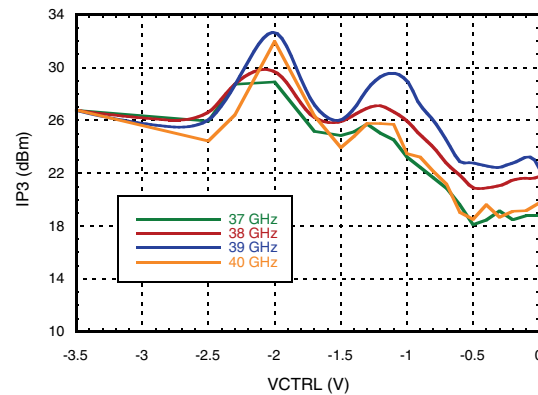


Data Taken as SSB Upconverter with External IF 90° Hybrid, IF = 1000 MHz

Input IP3, LSB vs. Control Voltage



Output IP3, LSB vs. Control Voltage



MxN Spurious Outputs [1][2]

	nLO				
mIF	0	1	2	3	4
0		31	4		
1	54	65	0		
2	62	71	40		
3	122	90	62		
4	122	122	122		
5	122	122	122		

IF = 2.35 GHz @ -8 dBm
LO = 17.575 GHz @ +4 dBm

MxN Spurious Outputs [1][2]

	nLO				
mIF	0	1	2	3	4
0		32	5		
1	56	59	0		
2	59	79	64		
3	118	118	68		
4	118	118	118		
5	118	118	118		

IF = 3 GHz @ -8 dBm
LO = 17.75 GHz @ +4 dBm

MxN Spurious Outputs [1][2]

	nLO				
mIF	0	1	2	3	4
0		31	5		
1	56	51	0		
2	61	70	48		
3	118	84	58		
4	122	122	122		
5	122	122	122		

IF = 4 GHz @ -8 dBm
LO = 17.75 GHz @ +4 dBm

MxN Spurious Outputs [1][2]

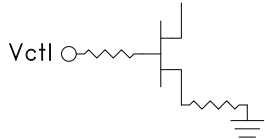
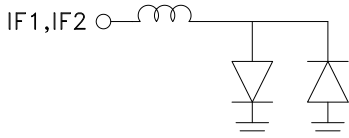
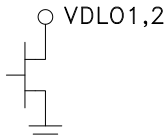
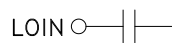
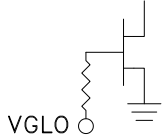
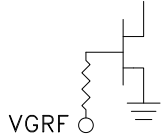
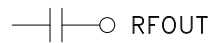
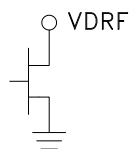
	nLO				
mIF	0	1	2	3	4
0		34	4		
1	59	54	0		
2	71	72	39		
3	120	86	62		
4	120	122	120		
5	120	120	120		

IF = 1 GHz @ -8 dBm
LO = 18.5 GHz @ +4 dBm

[1] Data taken without external IF 90° hybrid

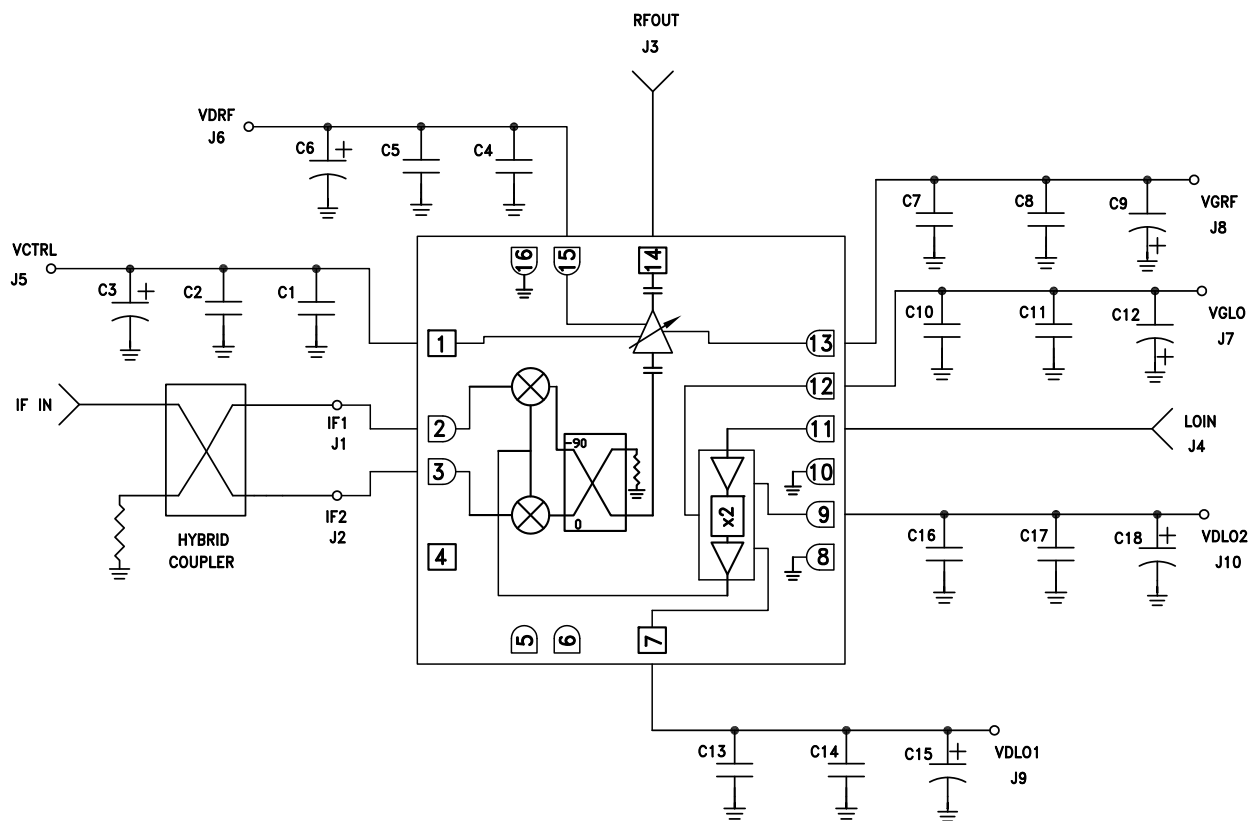
[2] All values in dBc below RF power level (2LO + IF) USB

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	VCTRL	Vary Vctrl from -3.5V to 0V to adjust conversion gain. Maximum Gain occurs at -3.5V. Current draw << 1 mA.	
2	IF1	Pins are DC coupled Must not source or sink more than +/- 3 mA for applications requiring operation to DC.	
3	IF2		
4, 5, 6	N/C	No connection required. The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
7	VDLO1	Bias for multiplier input buffer amp. The recommended DC voltage is +3V.	
9	VDLO2	Bias for multiplier input buffer amp. The recommended DC voltage is +3V.	
8, 10, 16	GND	These pins and package bottom must be connected to RF/DC ground.	
11	LOIN	LO input port. The recommended LO power is 0 to 8 dBm.	
12	VGLO	Adjust VGLO for -1V to 0V to set the multiplier quiescent current to 150 mA (200 - 230 mA with LO Drive).	
13	VGRF	Adjust VGRF for -1V to 0V to set the VGA current to 200 mA.	
14	RFOUT	RF output port.	
15	VDRF	Bias voltage for the VGA. The recommended DC voltage is +3V.	

GaAs MMIC I/Q UPCONVERTER 37 - 40 GHz

Typical Application



C1, C4, C7, C10, C13, C16	100 pF Capacitor, 0402 Pkg.
C2, C5, C8, C11, C14, C17	0.1 uF Capacitor, 0402 Pkg.
C3, C6, C9, C12, C15, C18	4.7 μ F Capacitor, Case A Pkg.



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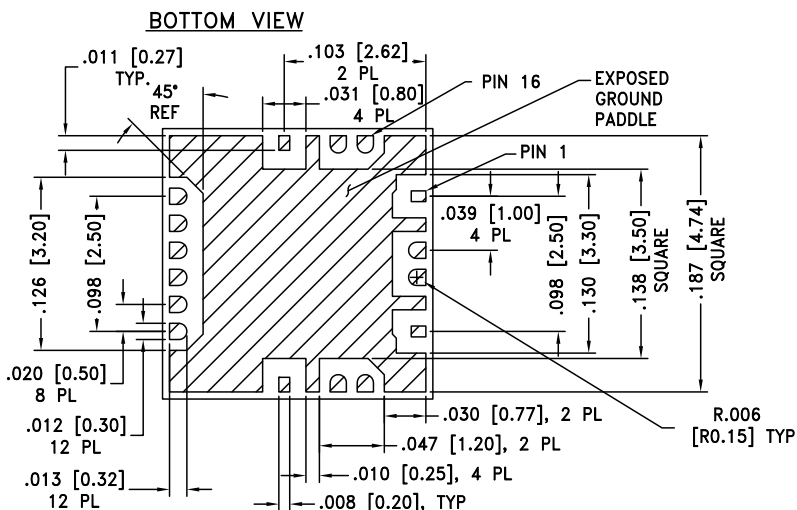


GaAs MMIC I/Q UPCONVERTER 37 - 40 GHz

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

IF Input	+20 dBm
LO Input	+10 dBm
Channel Temperature	175 °C
Continuous P _{diss} (T = 85°C) (derate 18.3 mW/°C above 85°C)	1.65 W
Thermal Resistance (channel to ground paddle)	54.6 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class1A

Figure 1: Dimensions of the H6787A. The diagram shows a rectangular component with a top surface and a side profile. The top surface has a width of 0.197 ± .005 inches (5.00 ± .13 mm) and a height of 0.197 ± .005 inches (5.00 ± .13 mm). The top surface is divided into two sections: a left section with a width of 0.033 inches (0.85 mm) MAX and a right section with a width of 0.164 inches (4.16 mm). The side profile shows a total height of 0.197 inches (5.00 mm) and a base width of 0.164 inches (4.16 mm). The top surface is labeled 'H6787A' and 'XXXX'. The side profile is labeled 'SEATING'.



NOTES:

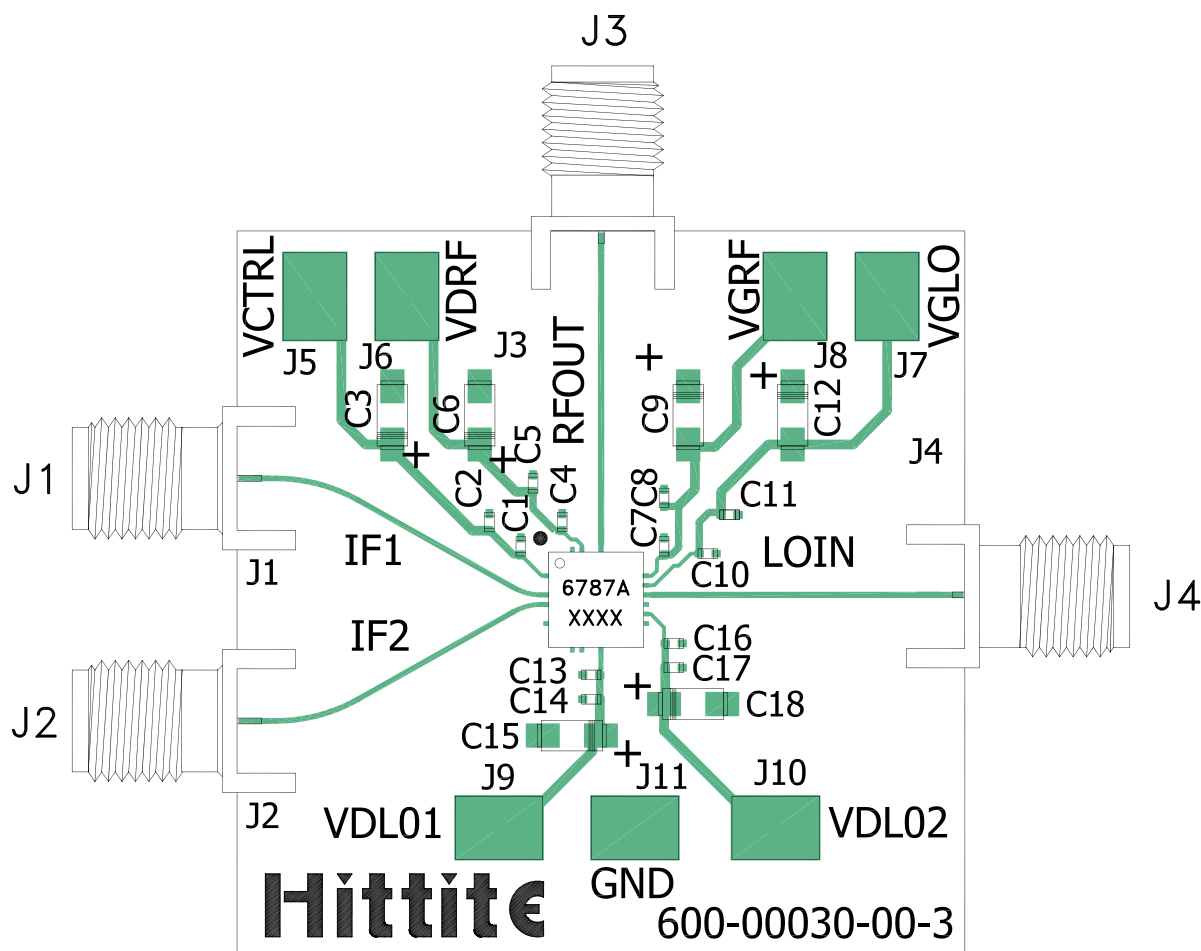
1. PACKAGE BODY MATERIAL: ALUMINA
2. LEAD AND GROUND PADDLE PLATING: 30 - 80 MICROINCHES
GOLD OVER 50 MICROINCHES MINIMUM NICKLE
3. DIMENSIONS ARE IN INCHES [MILLIMETERS]
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED
TO PCB RF GROUND

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[2]
HMC6787ALC5A	Alumina, White	Gold over Nickel	MSL3 ^[1]	6768A XXXX

[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX

Evaluation PCB



List of Materials for Evaluation PCB Eval01-HMC6787ALC5A ^[1]

Item	Description
J1, J2	SMA Connector
J3, J4	K-Connector SRI
J5 - J11	DC Pins
C1, C4, C7, C10, C13, C16	100 pF Capacitor, 0402 Pkg.
C2, C5, C8, C11, C14, C17	0.1 uF Capacitor, 0402 Pkg.
C3, C6, C9, C12, C15, C18	4.7 uF Capacitor, Case A
U1	HMC6787ALC5A Upconverter
PCB [2]	600-00030-00 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR, FR4 or Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



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HMC6787ALC5A

GaAs MMIC I/Q UPCONVERTER
37 - 40 GHz

Notes: